

ON Semiconductor **10/15/2019**

Base Part		KA4558		Pb-free
Orderable Part		KA4558	Total weight (mg)	478.247
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	1.6	Silicon (Si)	7440-21-3	100
Die Attach	3	Silver (Ag)	7440-22-4	75
		Phenolic Resin-2	54208-63-8	25
Lead Frame	137.787	Silver (Ag)	7440-22-4	0.50077293
		Zinc (Zn)	7440-66-6	0.14007127
		Iron (Fe)	7439-89-6	2.61272834
		Copper (Cu)	7440-50-8	96.52579706
		Phosphorus (P)	7723-14-0	0.22063039
Mold Compound-Black	320.81	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	1.83909479
		Ortho Cresol Novolac Resin	29690-82-2	18.51563231
		Antimony Trioxide (Sb2O3)	1309-64-4	1.83909479
		Carbon Black (C)	1333-86-4	0.50185468
		Fused Silica (SiO2)	60676-86-0	77.30432343
Plating	9.05	Tin (Sn)	7440-31-5	100
Wire Bond - Au	6	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>